

PCN Number:	20170630000		PCN Date:	June 30 2017									
Title:	Qualification of Hana Thailand as an additional Assembly and Test Site and for UCC27324/424 Devices												
Customer Contact:	PCN Manager	Dept:	Quality Services										
Proposed 1st Ship Date:	Sept 30 2017	Estimated Sample Availability:	Provided upon Request										
Change Type:													
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Assembly Materials								
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification								
<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process								
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process								
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process								
		<input type="checkbox"/>	Part number change										
PCN Details													
Description of Change:													
<p>Texas Instruments is pleased to announce the qualification of Hana Thailand as an additional Assembly and test site for the UCC27324/424 device family. Construction differences are as follows:</p> <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th>What</th> <th>ASESH</th> <th>Hana Thailand</th> </tr> </thead> <tbody> <tr> <td>Mount Compound</td> <td>SID#EY1000063</td> <td>SID#400154</td> </tr> <tr> <td>Mold Compound</td> <td>SID#EN2000515</td> <td>SID#450179</td> </tr> </tbody> </table> <p>Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.</p>					What	ASESH	Hana Thailand	Mount Compound	SID#EY1000063	SID#400154	Mold Compound	SID#EN2000515	SID#450179
What	ASESH	Hana Thailand											
Mount Compound	SID#EY1000063	SID#400154											
Mold Compound	SID#EN2000515	SID#450179											
Reason for Change:													
Continuity of Supply													
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):													
None													
Anticipated impact on Material Declaration													
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website .										

Changes to product identification resulting from this PCN:			
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City
ASESH	ASH	CHN	Shanghai
HNT	HNT	THA	Ayutthaya
Sample product shipping label (not actual product label)			



MADE IN: Malaysia
2DC: 2Q:

MSL 2 / 260C/1 YEAR	SEAL DT
MSL 1 / 235C/UNLIM	03/29/04

OPT:
ITEM:

LBL: 5A (L)T0:1750



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO: USA
(22L) ASO: MLA (23L) ACO: MYS

Topside Device marking (if included):

Assembly site code for ASH= A

Assembly site code for HNT = H

Product Affected

UCC27324DGN	UCC27324DGNR	UCC27424DGN	UCC27424DGNR
UCC27324DGNG4	UCC27324DGNRG4	UCC27424DGNG4	UCC27424DGNRG4



TI Information
Selective Disclosure

Qualification Report
UCC27324DGN Qual at HNT
Approve Date 31-May-2017

Product Attributes

Attributes	Qual Device: UCC27324DGN	QBS Package Reference: INA826AIDGK	QBS Package Reference: OPA2140AIDGK	QBS Package Reference: TPS7A4901DGN
Assembly Site	HANA -THAILAND	HANA -THAILAND	HANA -THAILAND	HANA -THAILAND
Package Family	HVSSOP	MSOP	MSOP	HVSSOP
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	DL-LIN-2	FFAB	FFAB	FREISING (FFAB)
Wafer Process	LBC3S	BICOM3XH	BICOM3HV	BICOM3XH

- QBS: Qual By Similarity
- Qual Device UCC27324DGN is qualified at LEVEL1-260CG

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: UCC27324DGN	QBS Package Reference: INA826AIDGK	QBS Package Reference: OPA2140AIDGK	QBS Package Reference: TPS7A4901DGN
AC	Autoclave 121C	96 Hours	-	-	1/77/0	1/77/0
CDM	ESD - CDM	1000 V	1/3/0	1/3/0	1/3/0	1/3/0
ED	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	2/35/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	1/77/0	-	1/77/0
HBM	ESD - HBM	4000 V	1/3/0	-	1/3/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	1/69/0	-
TC	Temperature Cycle -65/150C	500 Cycles	1/77/0	1/77/0	1/77/0	1/77/0
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	1/77/0	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -65C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
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